

C<sub>1</sub> simultaneously transferring a processed wafer and an unprocessed wafer between said loadlock chamber and said respective process chamber.

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C<sub>2</sub> 24. (Amended) A method of semiconductor wafer processing comprising the steps of:  
providing an atmospheric front end unit including a front end robot for transporting a semiconductor wafer, a multi-chamber module including a plurality of vertically-stacked semiconductor wafer process chambers, a loadlock chamber for each semiconductor wafer process chamber, and a wafer transfer apparatus for each loadlock chamber, each said loadlock chamber and each said wafer transfer apparatus dedicated to a respective wafer process chamber;  
transporting a wafer between said atmospheric front end unit and one of said loadlock chambers via said robot; and  
simultaneously transferring a processed and an unprocessed wafer between said one loadlock chamber and a respective wafer process chamber via said wafer transfer apparatus.

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Please add claims 25 and 26 to read as shown:

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Rule 1.12b  
C<sub>3</sub> ~~25, 26~~ (New) The method according to claim 19 wherein the simultaneous transferring is performed by a single-axis wafer transfer arm capable of providing an extended position and a home position.

~~26~~<sup>27</sup> (New) The method according to claim 24 wherein the simultaneous transferring is performed by a single-axis wafer transfer arm capable of providing an extended position and a home position.

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#### REMARKS

This amendment is submitted in response to the Office Action dated December 31, 2002. Claims 19 and 24 are amended. New claims 25 and 25 are added. Support for this amendment and addition are found in the specification and drawings. Claims 19-26 are pending in this application.

Claim Rejections under 35 U.S.C. 102: